

# 8A, 400V - 1000V Surface Mount Glass Passivated Rectifier

#### **FEATURES**

- Low forward voltage drop
- Ideal for automated placement
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

Δ	D	D	C	Δ	TI	0	N	S

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

#### **MECHANICAL DATA**

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Polarity: As marked
- Weight: 0.26 g (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
I <sub>F</sub>	8	Α			
$V_{RRM}$	400 - 1000	V			
I <sub>FSM</sub>	200	Α			
T <sub>J MAX</sub>	150 °C				
Package	DO-214AB (SMC)				









ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER	SYMBOL	S8GC -T	S8JC-T	S8KC-T	S8MC-T	UNIT
Marking code on the device		S8GC	S8JC	S8KC	S8MC	
Repetitive peak reverse voltage	$V_{RRM}$	400	600	800	1000	V
Reverse voltage, total rms value	V <sub>R(RMS)</sub>	280	420	560	700	V
Forward current at T <sub>L</sub> = 96 °C	I <sub>F</sub>			3		А
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I <sub>FSM</sub>		20	00		А
Junction temperature	T <sub>J</sub>		- 55 to	+150		°C
Storage temperature	T <sub>STG</sub>		- 55 to	+150		°C



THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP.	UNIT		
Junction-to-lead thermal resistance per diode	$R_{\Theta JL}$	8	°C/W		
Junction-to-ambient thermal resistance per diode	$R_{\Theta JA}$	54	°C/W		
Junction-to-case thermal resistance per diode	R <sub>eJC</sub>	9	°C/W		

Thermal Performance Note: Units mounted on PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP.	MAX.	UNIT
	I <sub>F</sub> = 4A, T <sub>J</sub> = 25°C		0.90	-	V
Forward voltage per diode (1)	I <sub>F</sub> = 8A, T <sub>J</sub> = 25°C	V <sub>F</sub>	0.96	1.15	V
Forward voltage per diode **	I <sub>F</sub> = 4A, T <sub>J</sub> = 125°C		0.78	-	V
	I <sub>F</sub> = 8A, T <sub>J</sub> = 125°C		0.86	0.99	V
Daviers august @ reted V and diede (2)	T <sub>J</sub> = 25°C	I <sub>R</sub>	-	10	μΑ
Reverse current @ rated V <sub>R</sub> per diode <sup>(2)</sup>	T <sub>J</sub> = 125°C		-	250	μΑ
Junction capacitance	1 MHz, V <sub>R</sub> =4.0V	CJ	53	-	pF

### Notes:

- 1. Pulse test with PW=0.3 ms
- Pulse test with PW=30 ms

ORDERING CODE	PACKAGE	PACKING
S8GC-T R7G	SMC	850 / 7" Plastic reel
S8GC-T M6G	SMC	3,000 / 13" Plastic reel
S8JC-T R7G	SMC	850 / 7" Plastic reel
S8JC-T M6G	SMC	3,000 / 13" Plastic reel
S8KC-T R7G	SMC	850 / 7" Plastic reel
S8KC-T M6G	SMC	3,000 / 13" Plastic reel
S8MC-T R7G	SMC	850 / 7" Plastic reel
S8MC-T M6G	SMC	3,000 / 13" Plastic reel



### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

10 AVERAGE FORWARD CURRENT (A) 8 6 2 Heat sink 16mm x 16mm Cu pad test board 0 50 75 100 25 125 150 LEAD TEMPERATURE (C)

Fig.2 Typical Junction Capacitance

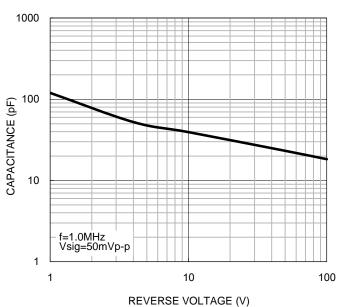
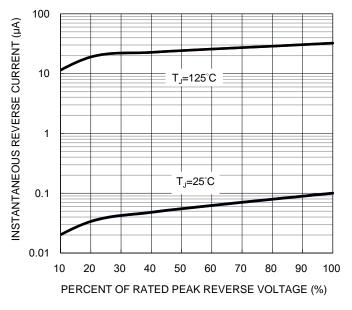
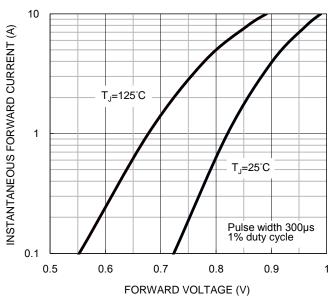


Fig.3 Typical Reverse Characteristics

Fig.4 Typical Forward Characteristics



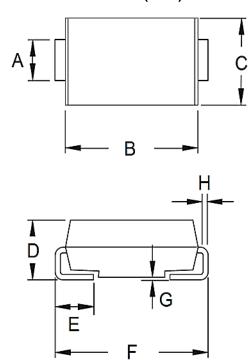


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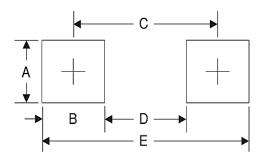
# **PACKAGE OUTLINE DIMENSIONS**

## DO-214AB (SMC)



DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min	Max	Min	Max	
Α	2.90	3.20	0.114	0.126	
В	6.60	7.11	0.260	0.280	
С	5.59	6.22	0.220	0.245	
D	2.00	2.62	0.079	0.103	
Е	1.00	1.60	0.039	0.063	
F	7.75	8.13	0.305	0.320	
G	0.10	0.20	0.004	0.008	
Н	0.15	0.31	0.006	0.012	

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)	
А	3.30	0.130	
В	2.50	0.098	
С	6.80	0.268	
D	4.40	0.173	
E	9.40	0.370	

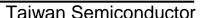
### **MARKING DIAGRAM**



P/N = Marking Code G =Green Compound

ΥW = Date Code F = Factory Code

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